MHF10N60CT

600V Silicon N-Channel Power MOSFET

■ Features

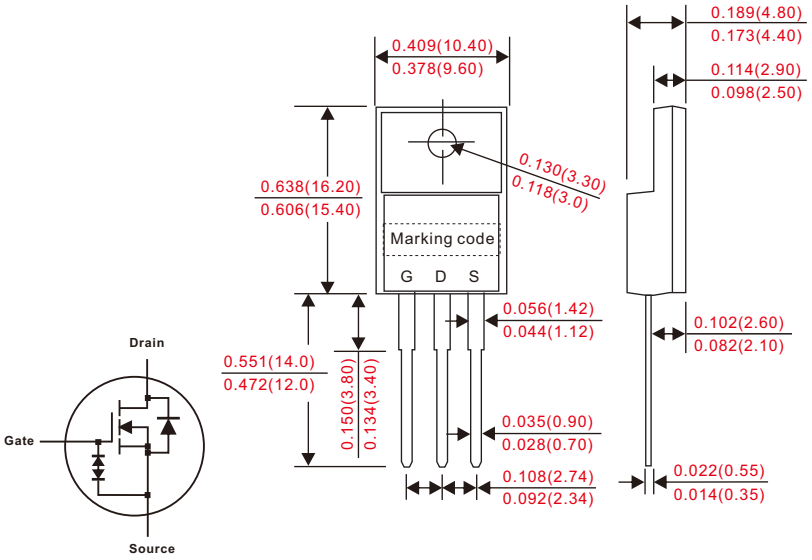
- Fast switching.
- ESD improved capability.
- Low gate charge.
- Low reverse transfer capacitances.
- 100% single pulse avalanche energy test.

■ Mechanical data

- Epoxy : UL94-V0 rated flame retardant.
- Case : JEDEC TO-220F molded plastic body.
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026.
- Polarity: As marked.
- Mounting Position : Any.
- Weight : Approximated 2.25 gram.

■ Outline

TO-220F



Dimensions in inches and (millimeters)

■ Absolute(T_C = 25°C unless otherwise specified)

PARAMETER	CONDITIONS	Symbol	MHF10N60CT	UNIT
Drain-Source Voltage		V_{DSS}	600	V
Continuous Drain Current		I_D	10	A
Continuous Drain Current	T_C = 100°C		8	
Pulsed Drain Current(1)		I_{DM}	40	
Gate-Source Voltage		V_{GS}	±30	V
Single Pulse Avalanche Energy(2)		E_{AS}	800	mJ
Avalanche Current(1)		I_{AR}	4.0	A
Repetitive Avalanche Energy(1)		E_{AR}	80	mJ
Power Dissipation		P_D	50	W
	Derating factor above 25°C		0.4	W/°C
Peak Diode Recovery dv/dt(3)		dV/dt	5.0	V/ns
Gate source ESD	HBM-C = 100pf, R = 1.5kΩ	$V_{ESD(G-S)}$	4000	V
Operating and Storage Temperature Range		T_J, T_{STG}	-55 ~ +150	°C
Maximum temperature for soldering		T_L	300	°C

NOTE : 1.Repetitive rating; pulse width limited by maximum junction temperature.
2.L=10.0mH, I_D = 12.6A, Start T_J = 25°C.
3.I_{SD} =10A,di/dt ≤100A/us, V_{DD}≤BV_{DS}, Start T_J = 25°C.

Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1

■ Electrical characteristics(T_C = 25°C unless otherwise specified)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA	V_{DSS}	600			V
Bvdss Temperature Coefficient	I_D = 250uA, Reference 25°C	BV_{DSS} / T_J		0.74		V/°C
Drain-Source Leakage Current	V_{DS} = 600V, V_{GS} = 0V, T_a = 25°C	I_{DSS}			1	uA
	V_{DS} = 480V, V_{GS} = 0V, T_a = 125°C				100	
Gate-Source Leakage Current, Forward	V_{GS} = 20V	$I_{GSS(F)}$			10	uA
Gate-Source Leakage Current, Reverse	V_{GS} = -20V	$I_{GSS(R)}$			-10	

■ ON Characteristics

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	$V_{GS(th)}$	2.0		4.0	V
Static Drain-Source On-Resistance	V_{GS} = 10V, I_D = 5A	$R_{DS(on)}$		0.6	0.75	Ω

■ Dynamic Characteristics

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward Transconductance	V_{DS} = 15V, I_D = 5A	g_{fs}		9		S
Input Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz	C_{iss}		1556		pF
Output Capacitance		C_{oss}		158		
Reverse Transfer Capacitance		C_{rss}		16		

■ Resistive Switching Characteristics

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Turn-on Delay Time	I_D = 10A, V_{DD} = 300V, V_{GS} = 10V, R_G = 4.7Ω	$td_{(ON)}$		12		ns
Rise Time		tr		16		
Turn-off Delay Time		$td_{(OFF)}$		39		
Fail Time		tf		17		
Total Gate Charge	I_D = 10A, V_{DD} = 300V, V_{GS} = 10V	Q_g		39		nC
Gate-Source Charge		Q_{gs}		7.4		
Gate-Drain Charge		Q_{gd}		16		

■ Source-Drain Diode Characteristics

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Continuous Source-Drain Diode Current	Boby Diode	I_S			10	A
Pulse Diode Forward Current	Boby Diode	I_{SM}			40	
Body Diode Voltage	I_S = 10A, V_{GS} = 0V	V_{SD}			1.5	V
Reverse recovery time	I_S = 10A, T_J = 25°C, dI_F/dt = 100A/μs, V_{GS} = 0V	t_{rr}		262		ns
Reverse recovery charge		Q_{rr}		1727		uC

■ Thermal characteristics

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Thermal Resistance	Junction to Case	$R_{\theta JC}$		2.5		°C/W
	Junction to Ambient	$R_{\theta JA}$		100		

■ Thermal characteristics

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Gate-Source Breakdown Voltage	I_{GS} = ±1mA(open Drain)	V_{GSO}	30			V

Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1

■ Rating and characteristic curves

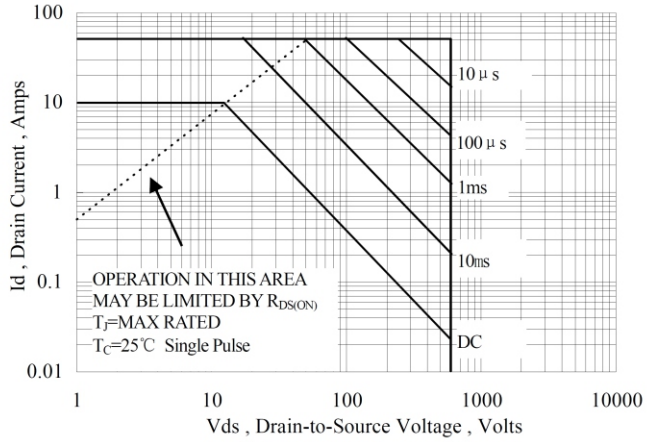


Figure 1 Maximun Forward Bias Safe Operating Area

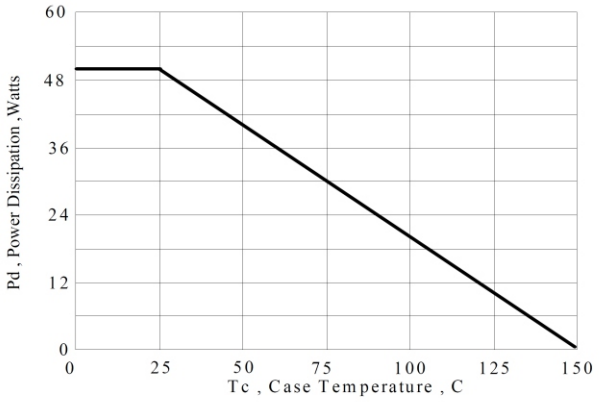


Figure 2 Maximun Power Dissipation vs Case Temperature

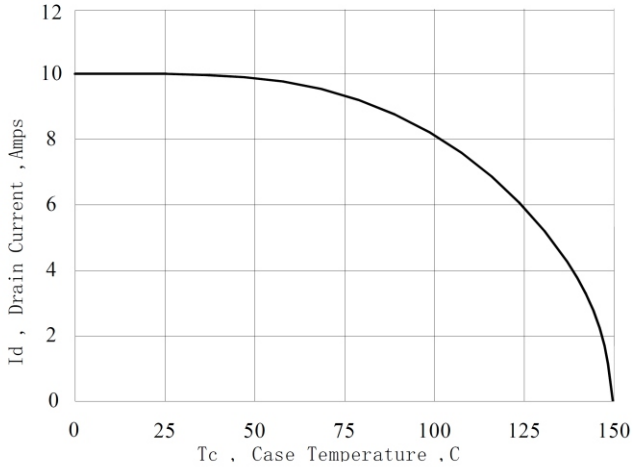


Figure 3 Maximum Continuous Drain Current vs Case Temperature

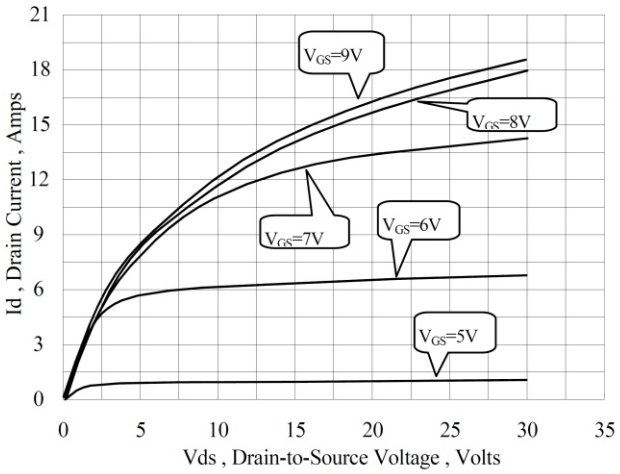


Figure 4 Typical Output Characteristics

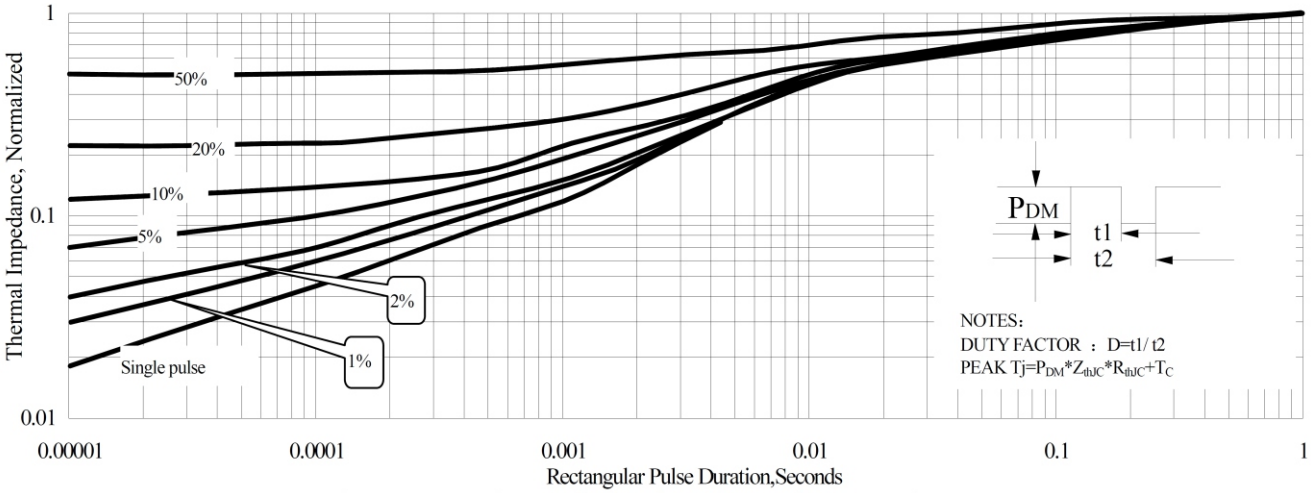


Figure 5 Maximum Effective Thermal Impendance , Junction to Case

Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1

■ Rating and characteristic curves

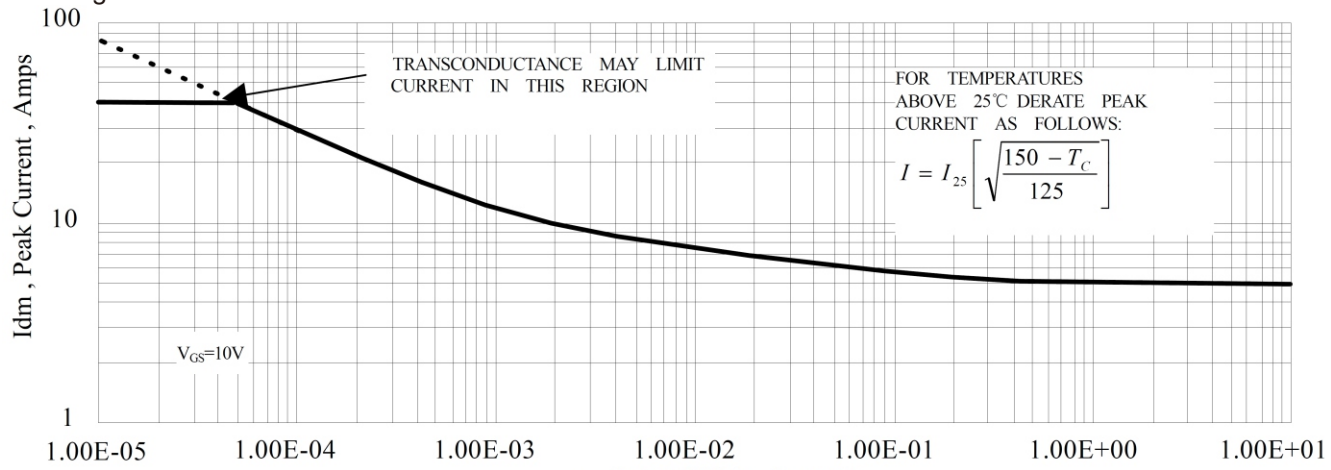


Figure 6 Maximun Peak Current Capability

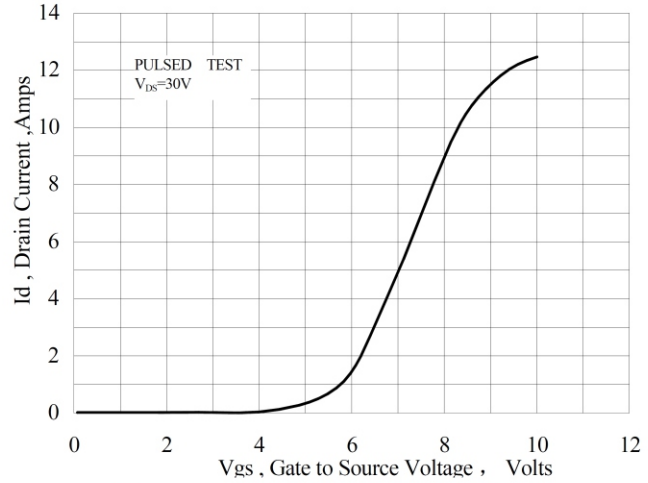


Figure 7 Typical Transfer Characteristics

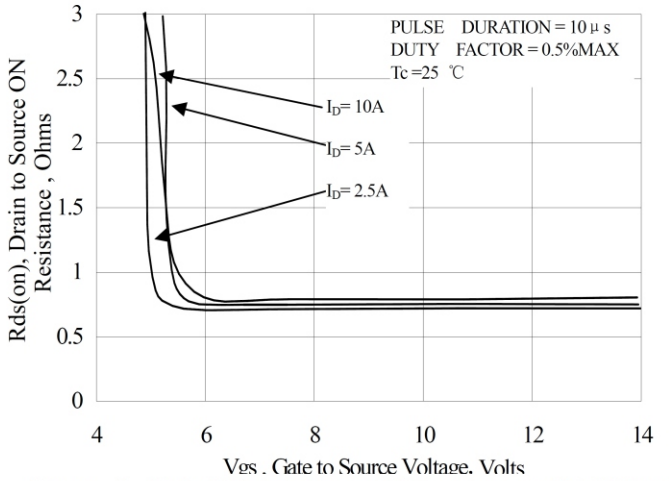


Figure 8 Typical Drain to Source ON Resistance vs Gate Voltage and Drain Current

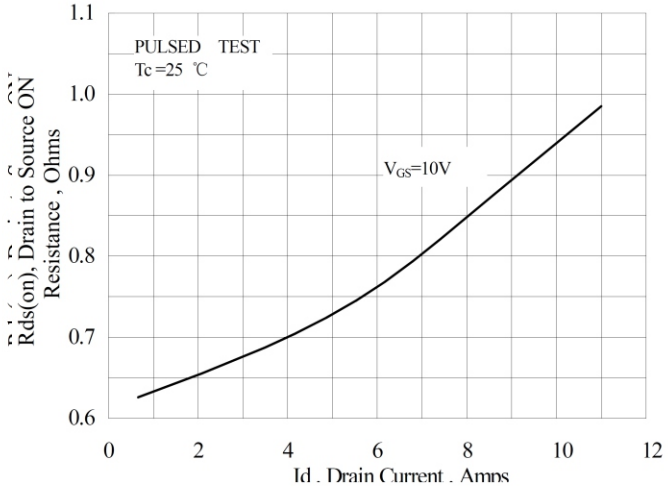


Figure 9 Typical Drain to Source ON Resistance vs Drain Current

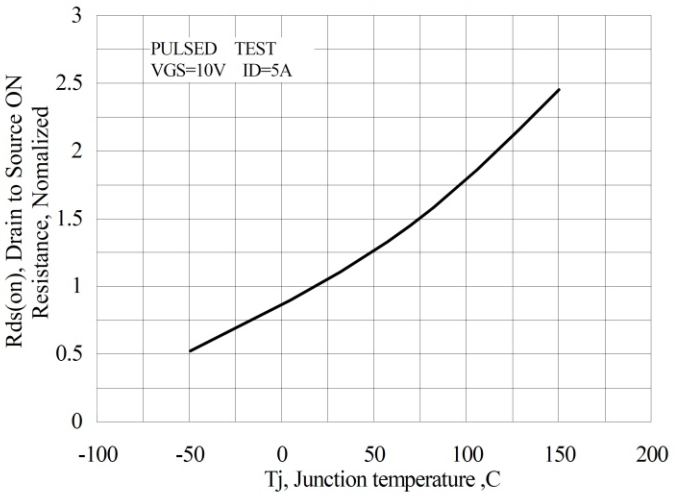


Figure 10 Typical Drian to Source on Resistance vs Junction Temperature

Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1

■ Rating and characteristic curves

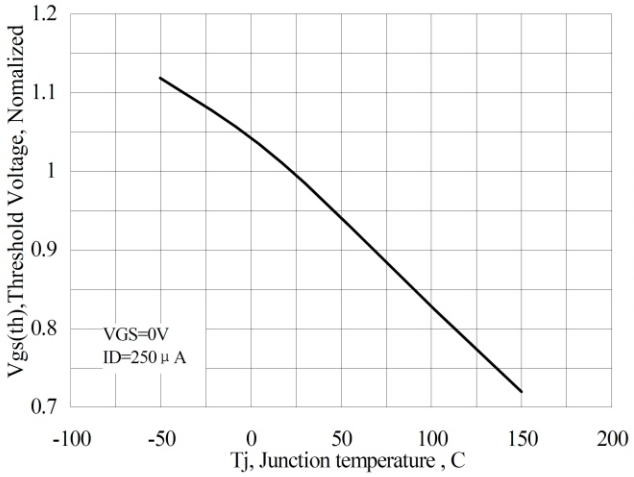


Figure 11 Typical Theshold Voltage vs Junction Temperature

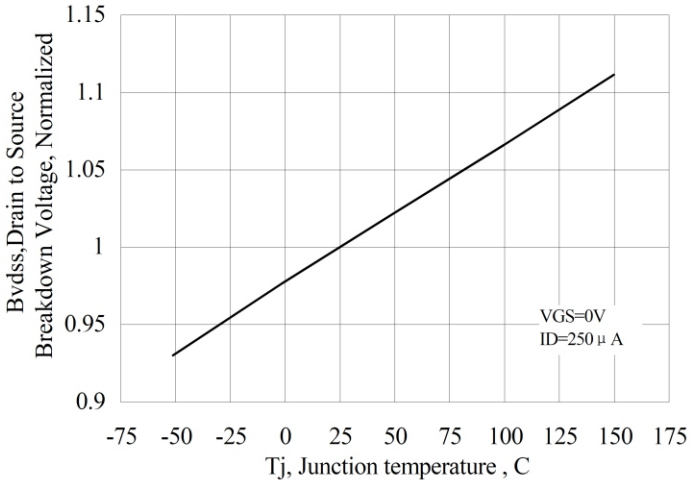


Figure 12 Typical Breakdown Voltage vs Junction Temperature

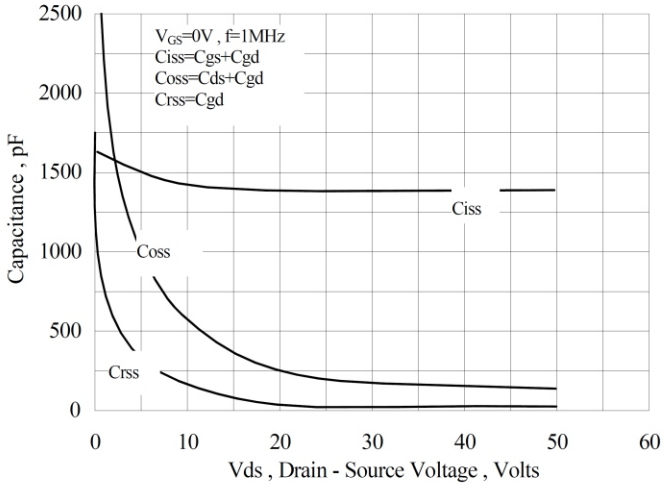


Figure 13 Typical Capacitance vs Drain to Source Voltage

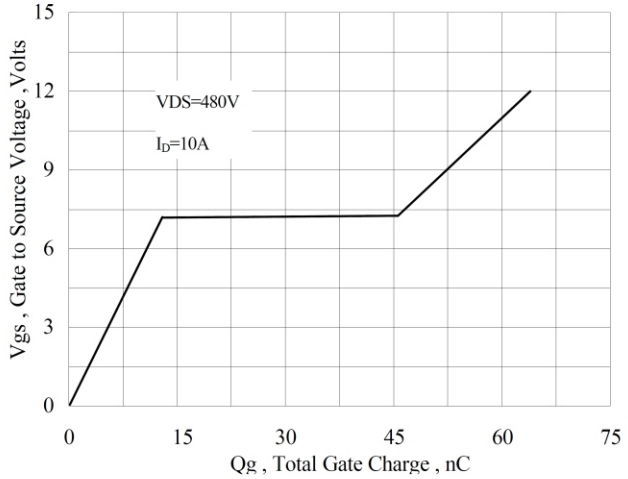


Figure 14 Typical Gate Charge vs Gate to Source Voltage

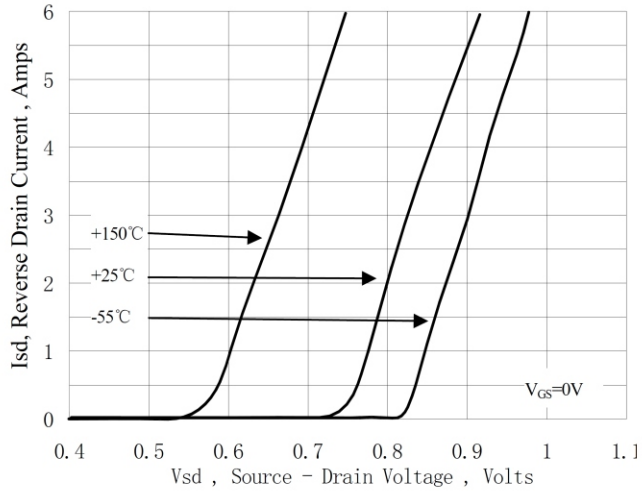


Figure 15 Typical Body Diode Transfer Characteristics

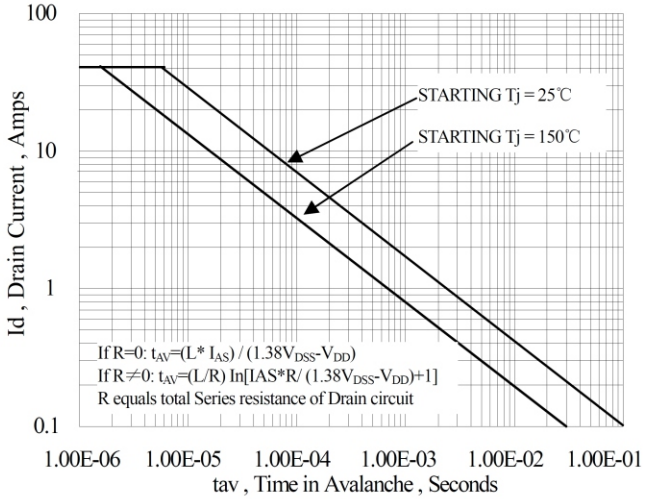


Figure 16 Unclamped Inductive Switching Capability

Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1

■ Test circuit and waveform

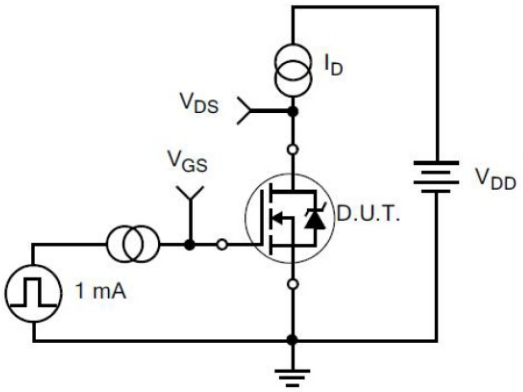


Figure 17. Gate Charge Test Circuit

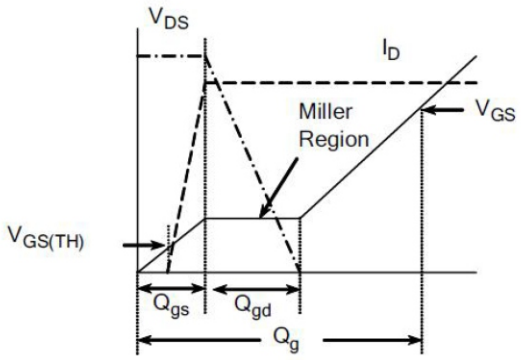


Figure 18. Gate Charge Waveform

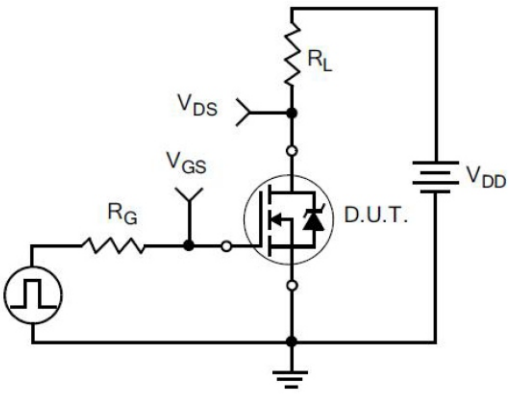


Figure 19. Resistive Switching Test Circuit

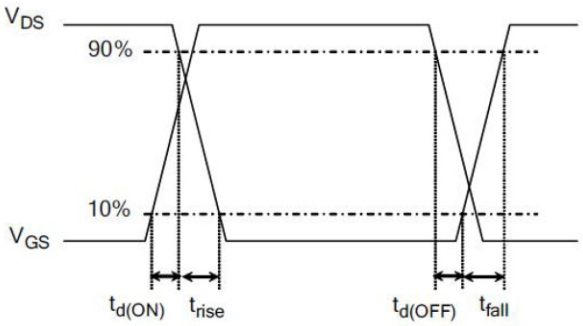


Figure 20. Resistive Switching Waveforms

Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1

■ Test circuit and waveform

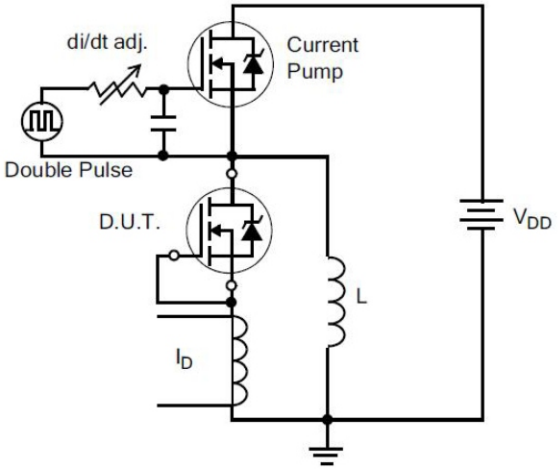


Figure 21. Diode Reverse Recovery Test Circuit

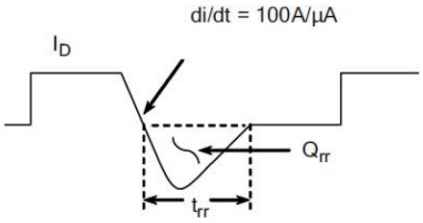


Figure 22. Diode Reverse Recovery Waveform

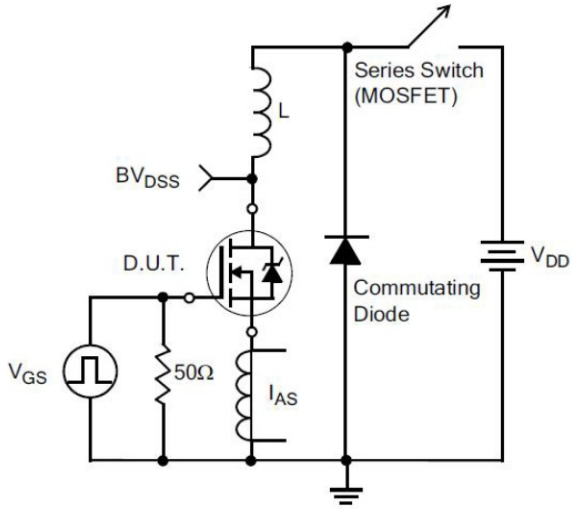
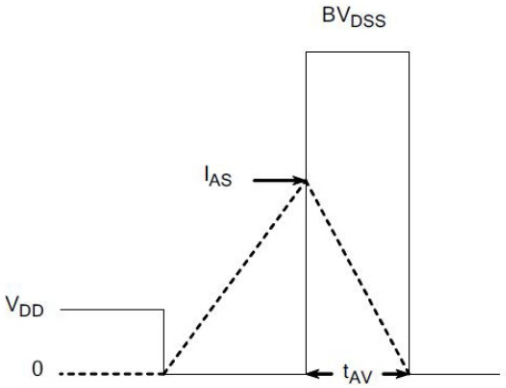


Figure 23. Unclamped Inductive Switching Test Circuit



$$E_{AS} = \frac{I_{AS}^2 L}{2}$$

Figure 24. Unclamped Inductive Switching Waveforms

Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1

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Document ID : DS-21M59
Revised Date : 2015/09/16
Revision : C1